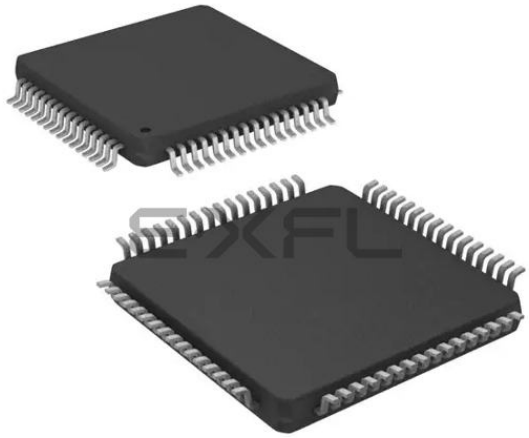

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, IrDA, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.98V ~ 3.8V
Data Converters	A/D 8x12b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32g232f32-qfp64

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3.3 Memory Map

The EFM32G memory map is shown in the figure below. RAM and Flash sizes are for the largest memory configuration.

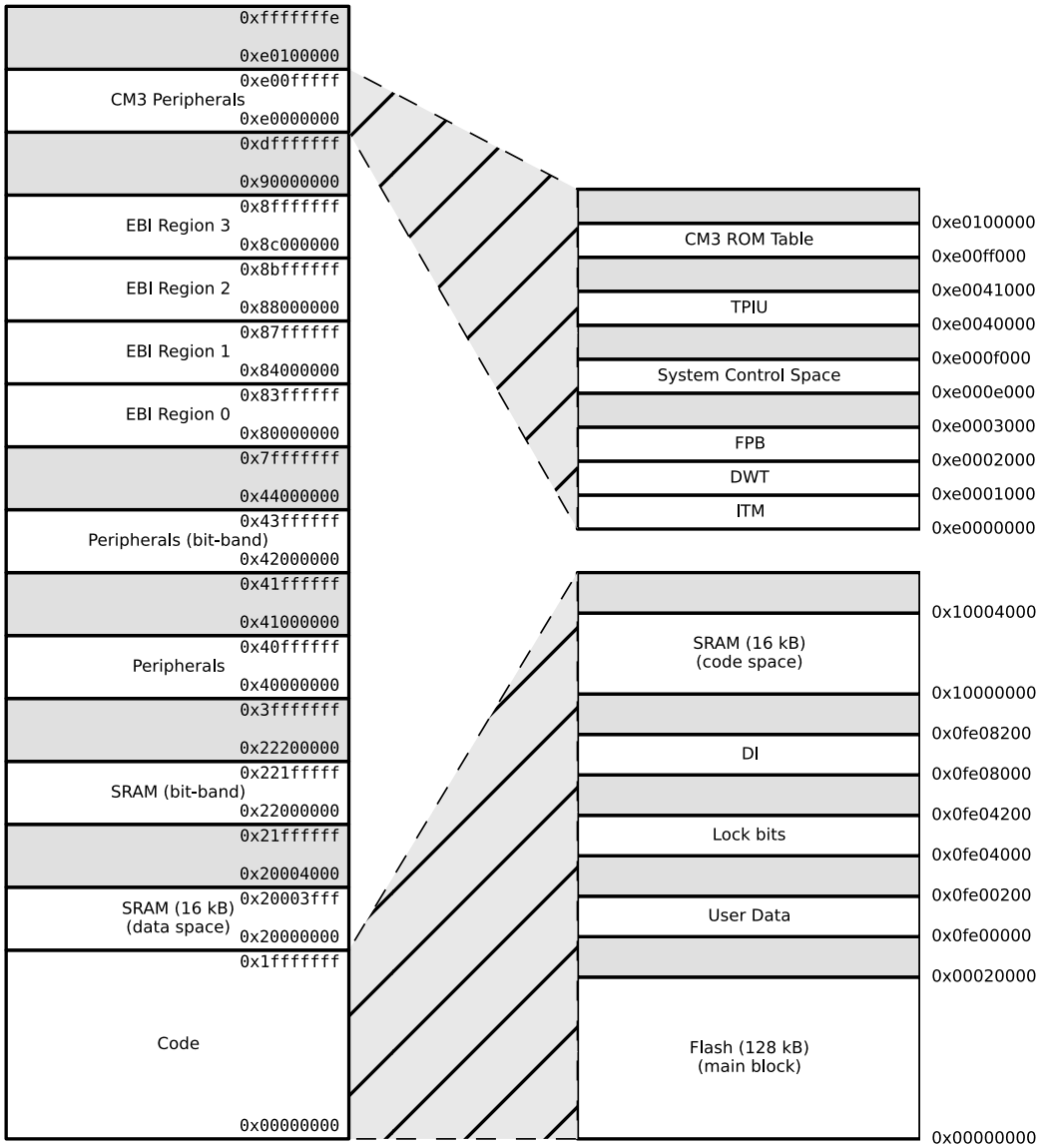

Figure 3.2. System Address Space with Core and Code Space Listing

4.9 Oscillators

4.9.1 LFXO

Table 4.8. LFXO

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Supported nominal crystal frequency	f_{LFXO}		—	32.768	—	kHz
Supported crystal equivalent series resistance (ESR)	ESR_{LFXO}		—	30	120	kOhm
Supported crystal external load range	C_{LFXOL}		X[1]	—	25	pF
Current consumption for core and buffer after startup	I_{LFXO}	ESR=30 kΩ, C_L=10 pF, LFXOBOOST in CMU_CTRL is 1	—	190	—	nA
Start-up time	t_{LFXO}	ESR=30 kΩ, C_L=10 pF, 40% - 60% duty cycle has been reached, LFXOBOOST in CMU_CTRL is 1	—	400	—	ms

Note:
1. See Minimum Load Capacitance (C_{LFXOL}) Requirement For Safe Crystal Startup in Configurator in Simplicity Studio.

For safe startup of a given crystal, the Configurator tool in Simplicity Studio contains a tool to help users configure both load capacitance and software settings for using the LFXO. For details regarding the crystal configuration, the reader is referred to application note "AN0016 EFM32 Oscillator Design Consideration".

4.9.4 HFRCO

Table 4.11. HFRCO

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Oscillation frequency, V_{DD}= 3.0 V, T_{AMB}=25 ºC	f_{HFRCO}	28 MHz frequency band	27.16	28	28.84	MHz
		21 MHz frequency band	20.37	21	21.63	MHz
		14 MHz frequency band	13.58	14	14.42	MHz
		11 MHz frequency band	10.67	11	11.33	MHz
		7 MHz frequency band	6.402	6.6[1]	6.798	MHz
		1 MHz frequency band	1.164	1.2[2]	1.236	MHz
Settling time	$t_{HFRCO\_settling}$	After start-up, f_{HFRCO} = 14 MHz	—	0.6	—	Cycles
		After band switch	—	25	—	Cycles
Current consumption (Production test condition = 14 MHz)	I_{HFRCO}	f_{HFRCO} = 28 MHz	—	158	190	µA
		f_{HFRCO} = 21 MHz	—	125	155	µA
		f_{HFRCO} = 14 MHz	—	99	120	µA
		f_{HFRCO} = 11 MHz	—	88	110	µA
		f_{HFRCO} = 6.6 MHz	—	72	90	µA
		f_{HFRCO} = 1.2 MHz	—	24	32	µA
Duty cycle	DC_{HFRCO}	f_{HFRCO} = 14 MHz	48.5	50	51	%
Frequency step for LSB change in TUNING value	$TUNESTEP_{HFRCO}$		—	0.3[3]	—	%

Note:

1. For devices with prod. rev. < 19, Typ = 7 MHz and Min/Max values not applicable.
2. For devices with prod. rev. < 19, Typ = 1 MHz and Min/Max values not applicable.
3. The TUNING field in the CMU_HFRCOCTRL register may be used to adjust the HFRCO frequency. There is enough adjustment range to ensure that the frequency bands above 7 MHz will always have some overlap across supply voltage and temperature. By using a stable frequency reference such as the LFXO or HFXO, a firmware calibration routine can vary the TUNING bits and the frequency band to maintain the HFRCO frequency at any arbitrary value between 7 MHz and 28 MHz across operating conditions.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input offset current	$I_{ADCOFFSETIN}$	VSS < VIN < VDD	-40	—	40	nA
ADC Clock Frequency	f_{ADCCLK}	BIASPROG=0x747	—	—	7	MHz
		BIASPROG=0xF4B	—	—	13	MHz
Conversion time	$t_{ADCCONV}$	6 bit	7	—	—	ADCCLK Cycles
		8 bit	11	—	—	ADCCLK Cycles
		12 bit	13	—	—	ADCCLK Cycles
Acquisition time	t_{ADCACQ}	Programmable	1	—	256	ADCCLK Cycles
Required acquisition time for VDD/3 reference	$t_{ADCACQVDD3}$		2	—	—	µs
Startup time of reference generator and ADC core	$t_{ADCSTART}$	NORMAL mode	—	5	—	µs
		KEEPADCWARM mode	—	1	—	µs

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Signal-to-Noise Ratio (SNR)	SNR_{ADC}	1 MSamples/s, 12 bit, single-ended, internal 1.25 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	59	—	dB
		1 MSamples/s, 12 bit, single-ended, internal 2.5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	63	—	dB
		1 MSamples/s, 12 bit, single-ended, V_{DD} reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	67	—	dB
		1 MSamples/s, 12 bit, differential, internal 1.25 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	63	—	dB
		1 MSamples/s, 12 bit, differential, internal 2.5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	66	—	dB
		1 MSamples/s, 12 bit, differential, 5 V reference, ADC_CLK =13 MHz, BIASPROG = 0xF4B	—	66	—	dB
		1 MSamples/s, 12 bit, differential, V_{DD} reference, ADC_CLK= 13 MHz, BIASPROG =0xF4B	63	69	—	dB
		1 MSamples/s, 12 bit, differential, $2xV_{DD}$ reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	70	—	dB
		200 kSamples/s, 12 bit, single-ended, internal 1.25 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	62	—	dB
		200 kSamples/s, 12 bit, single-ended, internal 2.5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	63	—	dB
		200 kSamples/s, 12 bit, single-ended, V_{DD} reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	67	—	dB
		200 kSamples/s, 12 bit, differential, internal 1.25 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	63	—	dB
		200 kSamples/s, 12 bit, differential, internal 2.5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	66	—	dB
		200 kSamples/s, 12 bit, differential, 5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	66	—	dB

4.15 I2C

Table 4.19. I2C Standard-mode (Sm)

Parameter	Symbol	Min	Typ	Max	Unit
SCL clock frequency	f_{SCL}	0	—	100[1]	kHz
SCL clock low time	t_{LOW}	4.7	—	—	µs
SCL clock high time	t_{HIGH}	4.0	—	—	µs
SDA set-up time	$t_{SU,DAT}$	250	—	—	ns
SDA hold time	$t_{HD,DAT}$	8	—	3450[2,3]	ns
Repeated START condition set-up time	$t_{SU,STA}$	4.7	—	—	µs
(Repeated) START condition hold time	$t_{HD,STA}$	4.0	—	—	µs
STOP condition set-up time	$t_{SU,STO}$	4.0	—	—	µs
Bus free time between a STOP and a START condition	t_{BUF}	4.7	—	—	µs

Note:
1. For the minimum HFPERCLK frequency required in Standard-mode, see the I2C chapter in the EFM32G Reference Manual.
2. The maximum SDA hold time ($t_{HD,DAT}$) needs to be met only when the device does not stretch the low time of SCL (t_{LOW}).
3. When transmitting data, this number is guaranteed only when I2Cn_CLKDIV < ((3450*10^{-9} [s] * $f_{HFPERCLK}$ [Hz]) - 4).

Table 4.20. I2C Fast-mode (Fm)

Parameter	Symbol	Min	Typ	Max	Unit
SCL clock frequency	f_{SCL}	0	—	400[1]	kHz
SCL clock low time	t_{LOW}	1.3	—	—	µs
SCL clock high time	t_{HIGH}	0.6	—	—	µs
SDA set-up time	$t_{SU,DAT}$	100	—	—	ns
SDA hold time	$t_{HD,DAT}$	8	—	900[2,3]	ns
Repeated START condition set-up time	$t_{SU,STA}$	0.6	—	—	µs
(Repeated) START condition hold time	$t_{HD,STA}$	0.6	—	—	µs
STOP condition set-up time	$t_{SU,STO}$	0.6	—	—	µs
Bus free time between a STOP and a START condition	t_{BUF}	1.3	—	—	µs

Note:
1. For the minimum HFPERCLK frequency required in Fast-mode, see the I2C chapter in the EFM32G Reference Manual.
2. The maximum SDA hold time ($t_{HD,DAT}$) needs to be met only when the device does not stretch the low time of SCL (t_{LOW}).
3. When transmitting data, this number is guaranteed only when I2Cn_CLKDIV < ((900*10^{-9} [s] * $f_{HFPERCLK}$ [Hz]) - 4).

QFN32 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
31	PE12		TIM1_CC2 #1	US0_CLK #0	
32	PE13			US0_CS #0	ACMP0_O #0

TQFP48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
38	PF1		LETIM0_OUT1 #2		DBG_SWDIO #0/1
39	PF2				ACMP1_O #0 DBG_SWO #0
40	PF3		TIM0_CDTI0 #2		
41	PF4		TIM0_CDTI1 #2		
42	PF5		TIM0_CDTI2 #2		
43	IOVDD_5	Digital IO power supply 5.			
44	VSS	Ground.			
45	PE10		TIM1_CC0 #1	US0_TX #0	BOOT_TX
46	PE11		TIM1_CC1 #1	US0_RX #0	BOOT_RX
47	PE12		TIM1_CC2 #1	US0_CLK #0	
48	PE13			US0_CS #0	ACMP0_O #0

LQFP100 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
6	PA5		EBI_AD14 #0	TIM0_CDTI2 #0	LEU1_TX #1	
7	PA6		EBI_AD15 #0		LEU1_RX #1	
8	IOVDD_0	Digital IO power supply 0.				
9	PB0			TIM1_CC0 #2		
10	PB1			TIM1_CC1 #2		
11	PB2			TIM1_CC2 #2		
12	PB3			PCNT1_S0IN #1	US2_TX #1	
13	PB4			PCNT1_S1IN #1	US2_RX #1	
14	PB5				US2_CLK #1	
15	PB6				US2_CS #1	
16	VSS	Ground.				
17	IOVDD_1	Digital IO power supply 1.				
18	PC0	ACMP0_CH0		PCNT0_S0IN #2	US1_TX #0	
19	PC1	ACMP0_CH1		PCNT0_S1IN #2	US1_RX #0	
20	PC2	ACMP0_CH2			US2_TX #0	
21	PC3	ACMP0_CH3			US2_RX #0	
22	PC4	ACMP0_CH4		LETIM0_OUT0 #3 PCNT1_S0IN #0	US2_CLK #0	
23	PC5	ACMP0_CH5		LETIM0_OUT1 #3 PCNT1_S1IN #0	US2_CS #0	
24	PB7	LFXTAL_P			US1_CLK #0	
25	PB8	LFXTAL_N			US1_CS #0	
26	PA7					
27	PA8			TIM2_CC0 #0		
28	PA9			TIM2_CC1 #0		
29	PA10			TIM2_CC2 #0		
30	PA11					
31	IOVDD_2	Digital IO power supply 2.				
32	VSS	Ground.				
33	PA12			TIM2_CC0 #1		
34	PA13			TIM2_CC1 #1		
35	PA14			TIM2_CC2 #1		
36	RESETn	Reset input, active low.To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.				

LQFP100 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
63	PE3					ACMP1_O #1
64	PE4				US0_CS #1	
65	PE5				US0_CLK #1	
66	PE6				US0_RX #1	
67	PE7				US0_TX #1	
68	PC8	ACMP1_CH0		TIM2_CC0 #2	US0_CS #2	
69	PC9	ACMP1_CH1		TIM2_CC1 #2	US0_CLK #2	
70	PC10	ACMP1_CH2		TIM2_CC2 #2	US0_RX #2	
71	PC11	ACMP1_CH3			US0_TX #2	
72	PC12	ACMP1_CH4				CMU_CLK0 #1
73	PC13	ACMP1_CH5		TIM0_CDTI0 #1/3 TIM1_CC0 #0 PCNT0_S0IN #0		
74	PC14	ACMP1_CH6		TIM0_CDTI1 #1/3 TIM1_CC1 #0 PCNT0_S1IN #0	U0_TX #3	
75	PC15	ACMP1_CH7		TIM0_CDTI2 #1/3 TIM1_CC2 #0	U0_RX #3	DBG_SWO #1
76	PF0			LETIM0_OUT0 #2		DBG_SWCLK #0/1
77	PF1			LETIM0_OUT1 #2		DBG_SWDIO #0/1
78	PF2		EBI_ARDY #0			ACMP1_O #0 DBG_SWO #0
79	PF3		EBI_ALE #0	TIM0_CDTI0 #2		
80	PF4		EBI_WEn #0	TIM0_CDTI1 #2		
81	PF5		EBI_REn #0	TIM0_CDTI2 #2		
82	IOVDD_5	Digital IO power supply 5.				
83	VSS	Ground.				
84	PF6			TIM0_CC0 #2	U0_TX #0	
85	PF7			TIM0_CC1 #2	U0_RX #0	
86	PF8			TIM0_CC2 #2		
87	PF9					
88	PD9		EBI_CS0 #0			
89	PD10		EBI_CS1 #0			
90	PD11		EBI_CS2 #0			
91	PD12		EBI_CS3 #0			

5.7.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

Note: Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

Table 5.20. Alternate functionality overview

Alternate	LOCATION				
Functionality	0	1	2	3	Description
ACMP0_CH4	PC4				Analog comparator ACMP0, channel 4.
ACMP0_CH5	PC5				Analog comparator ACMP0, channel 5.
ACMP0_CH6	PC6				Analog comparator ACMP0, channel 6.
ACMP0_CH7	PC7				Analog comparator ACMP0, channel 7.
ACMP0_O	PE13				Analog comparator ACMP0, digital output.
ACMP1_CH4	PC12				Analog comparator ACMP1, channel 4.
ACMP1_CH5	PC13				Analog comparator ACMP1, channel 5.
ACMP1_CH6	PC14				Analog comparator ACMP1, channel 6.
ACMP1_CH7	PC15				Analog comparator ACMP1, channel 7.
ACMP1_O	PF2				Analog comparator ACMP1, digital output.
ADC0_CH0	PD0				Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PD1				Analog to digital converter ADC0, input channel number 1.
ADC0_CH2	PD2				Analog to digital converter ADC0, input channel number 2.
ADC0_CH3	PD3				Analog to digital converter ADC0, input channel number 3.
ADC0_CH4	PD4				Analog to digital converter ADC0, input channel number 4.
ADC0_CH5	PD5				Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6				Analog to digital converter ADC0, input channel number 6.
ADC0_CH7	PD7				Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PE11				Bootloader RX.
BOOT_TX	PE10				Bootloader TX.
CMU_CLK0	PA2	PC12			Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8			Clock Management Unit, clock output number 1.
DAC0_OUT0	PB11				Digital to Analog Converter DAC0 output channel number 0.
DAC0_OUT1	PB12				Digital to Analog Converter DAC0 output channel number 1.
DBG_SWCLK	PF0	PF0			Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1	PF1			Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.

Alternate	LOCATION				
Functionality	0	1	2	3	Description
DBG_SWO	PF2	PC15			Debug-interface Serial Wire viewer Output. Note that this function is not enabled after reset, and must be enabled by software to be used.
HFXTAL_N	PB14				High Frequency Crystal negative pin. Also used as external optional clock input pin.
HFXTAL_P	PB13				High Frequency Crystal positive pin.
I2C0_SCL	PA1	PD7	PC7		I2C0 Serial Clock Line input / output.
I2C0_SDA	PA0	PD6	PC6		I2C0 Serial Data input / output.
LCD_BCAP_N	PA13				LCD voltage booster (optional), boost capacitor, negative pin. If using the LCD voltage booster, connect a 22 nF capacitor between LCD_BCAP_N and LCD_BCAP_P.
LCD_BCAP_P	PA12				LCD voltage booster (optional), boost capacitor, positive pin. If using the LCD voltage booster, connect a 22 nF capacitor between LCD_BCAP_N and LCD_BCAP_P.
LCD_BEXT	PA14				LCD voltage booster (optional), boost output. If using the LCD voltage booster, connect a 1 uF capacitor between this pin and VSS. An external LCD voltage may also be applied to this pin if the booster is not enabled. If AVDD is used directly as the LCD supply voltage, this pin may be left unconnected or used as a GPIO.
LCD_COM0	PE4				LCD driver common line number 0.
LCD_COM1	PE5				LCD driver common line number 1.
LCD_COM2	PE6				LCD driver common line number 2.
LCD_COM3	PE7				LCD driver common line number 3.
LCD_SEG0	PF2				LCD segment line 0. Segments 0, 1, 2 and 3 are controlled by SEGEN0.
LCD_SEG1	PF3				LCD segment line 1. Segments 0, 1, 2 and 3 are controlled by SEGEN0.
LCD_SEG2	PF4				LCD segment line 2. Segments 0, 1, 2 and 3 are controlled by SEGEN0.
LCD_SEG3	PF5				LCD segment line 3. Segments 0, 1, 2 and 3 are controlled by SEGEN0.
LCD_SEG4	PE8				LCD segment line 4. Segments 4, 5, 6 and 7 are controlled by SEGEN1.
LCD_SEG5	PE9				LCD segment line 5. Segments 4, 5, 6 and 7 are controlled by SEGEN1.
LCD_SEG6	PE10				LCD segment line 6. Segments 4, 5, 6 and 7 are controlled by SEGEN1.
LCD_SEG7	PE11				LCD segment line 7. Segments 4, 5, 6 and 7 are controlled by SEGEN1.
LCD_SEG8	PE12				LCD segment line 8. Segments 8, 9, 10 and 11 are controlled by SEGEN2.

Alternate	LOCATION				
Functionality	0	1	2	3	Description
DAC0_OUT0	PB11				Digital to Analog Converter DAC0 output channel number 0.
DAC0_OUT1	PB12				Digital to Analog Converter DAC0 output channel number 1.
DBG_SWCLK	PF0	PF0			Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1	PF1			Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
DBG_SWO	PF2	PC15			Debug-interface Serial Wire viewer Output. Note that this function is not enabled after reset, and must be enabled by software to be used.
EBI_AD00	PE8				External Bus Interface (EBI) address and data input / output pin 00.
EBI_AD01	PE9				External Bus Interface (EBI) address and data input / output pin 01.
EBI_AD02	PE10				External Bus Interface (EBI) address and data input / output pin 02.
EBI_AD03	PE11				External Bus Interface (EBI) address and data input / output pin 03.
EBI_AD04	PE12				External Bus Interface (EBI) address and data input / output pin 04.
EBI_AD05	PE13				External Bus Interface (EBI) address and data input / output pin 05.
EBI_AD06	PE14				External Bus Interface (EBI) address and data input / output pin 06.
EBI_AD07	PE15				External Bus Interface (EBI) address and data input / output pin 07.
EBI_AD08	PA15				External Bus Interface (EBI) address and data input / output pin 08.
EBI_AD09	PA0				External Bus Interface (EBI) address and data input / output pin 09.
EBI_AD10	PA1				External Bus Interface (EBI) address and data input / output pin 10.
EBI_AD11	PA2				External Bus Interface (EBI) address and data input / output pin 11.
EBI_AD12	PA3				External Bus Interface (EBI) address and data input / output pin 12.
EBI_AD13	PA4				External Bus Interface (EBI) address and data input / output pin 13.
EBI_AD14	PA5				External Bus Interface (EBI) address and data input / output pin 14.
EBI_AD15	PA6				External Bus Interface (EBI) address and data input / output pin 15.
EBI_ALE	PF3				External Bus Interface (EBI) Address Latch Enable output.

Alternate	LOCATION				
Functionality	0	1	2	3	Description
LCD_SEG30	PD11				LCD segment line 30. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG31	PD12				LCD segment line 31. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG32	PB0				LCD segment line 32. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG33	PB1				LCD segment line 33. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG34	PB2				LCD segment line 34. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG35	PA7				LCD segment line 35. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG36	PA8				LCD segment line 36. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG37	PA9				LCD segment line 37. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG38	PA10				LCD segment line 38. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG39	PA11				LCD segment line 39. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LETIM0_OUT0	PD6	PB11	PF0	PC4	Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	PD7	PB12	PF1	PC5	Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14	PE15		LEUART0 Receive input.
LEU0_TX	PD4	PB13	PE14		LEUART0 Transmit output. Also used as receive input in half duplex communication.
LEU1_RX	PC7	PA6			LEUART1 Receive input.
LEU1_TX	PC6	PA5			LEUART1 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8				Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7				Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN	PC13	PE0	PC0		Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14	PE1	PC1		Pulse Counter PCNT0 input number 1.
PCNT1_S0IN	PC4	PB3			Pulse Counter PCNT1 input number 0.
PCNT1_S1IN	PC5	PB4			Pulse Counter PCNT1 input number 1.
PCNT2_S0IN	PD0	PE8			Pulse Counter PCNT2 input number 0.
PCNT2_S1IN	PD1	PE9			Pulse Counter PCNT2 input number 1.
TIM0_CC0	PA0	PA0	PF6	PD1	Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1	PF7	PD2	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2	PF8	PD3	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0	PA3	PC13	PF3	PC13	Timer 0 Complimentary Deat Time Insertion channel 0.

BGA112 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
C3	PE10	LCD_SEG 6	EBI_AD02 #0	TIM1_CC0 #1	US0_TX #0	BOOT_TX
C4	PD13					
C5	PD12	LCD_SEG 31	EBI_CS3 #0			
C6	PF9	LCD_SEG 27				
C7	VSS	Ground.				
C8	PF2	LCD_SEG 0	EBI_ARDY #0			ACMP1_O #0 DBG_SWO #0
C9	PE6	LCD_COM 2			US0_RX #1	
C10	PC10	ACMP1_CH2		TIM2_CC2 #2	US0_RX #2	
C11	PC11	ACMP1_CH3			US0_TX #2	
D1	PA3	LCD_SEG 16	EBI_AD12 #0	TIM0_CDTI0 #0	U0_TX #2	
D2	PA2	LCD_SEG 15	EBI_AD11 #0	TIM0_CC2 #0/1		CMU_CLK0 #0
D3	PB15					
D4	VSS	Ground.				
D5	IOVDD_6	Digital IO power supply 6.				
D6	PD9	LCD_SEG 28	EBI_CS0 #0			
D7	IOVDD_5	Digital IO power supply 5.				
D8	PF1			LETIM0_OUT1 #2		DBG_SWDIO #0/1
D9	PE7	LCD_COM 3			US0_TX #1	
D10	PC8	ACMP1_CH0		TIM2_CC0 #2	US0_CS #2	
D11	PC9	ACMP1_CH1		TIM2_CC1 #2	US0_CLK #2	
E1	PA6	LCD_SEG 19	EBI_AD15 #0		LEU1_RX #1	
E2	PA5	LCD_SEG 18	EBI_AD14 #0	TIM0_CDTI2 #0	LEU1_TX #1	
E3	PA4	LCD_SEG 17	EBI_AD13 #0	TIM0_CDTI1 #0	U0_RX #2	
E4	PB0	LCD_SEG 32		TIM1_CC0 #2		
E8	PF0			LETIM0_OUT0 #2		DBG_SWCLK #0/1

BGA112 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
H9	PD5	ADC0_CH 5			LEU0_RX #0	
H10	PD6	ADC0_CH 6		LETIM0_OUT0 #0	I2C0_SDA #1	
H11	PD7	ADC0_CH 7		LETIM0_OUT1 #0	I2C0_SCL #1	
J1	PC1	ACMP0_C H1		PCNT0_S1IN #2	US1_RX #0	
J2	PC3	ACMP0_C H3			US2_RX #0	
J3	PD15				I2C0_SCL #3	
J4	PA12	LCD_BCA P_P		TIM2_CC0 #1		
J5	PA9	LCD_SEG 37		TIM2_CC1 #0		
J6	PA10	LCD_SEG 38		TIM2_CC2 #0		
J7	PB9					
J8	PB10					
J9	PD2	ADC0_CH 2		TIM0_CC1 #3	US1_CLK #1	
J10	PD3	ADC0_CH 3		TIM0_CC2 #3	US1_CS #1	
J11	PD4	ADC0_CH 4			LEU0_TX #0	
K1	PB7	LFXTAL_P			US1_CLK #0	
K2	PC4	ACMP0_C H4		LETIM0_OUT0 #3 PCNT1_S0IN #0	US2_CLK #0	
K3	PA13	LCD_BCA P_N		TIM2_CC1 #1		
K4	VSS	Ground.				
K5	PA11	LCD_SEG 39				
K6	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.				
K7	AVSS_1	Analog ground 1.				
K8	AVDD_2	Analog power supply 2.				
K9	AVDD_1	Analog power supply 1.				
K10	AVSS_0	Analog ground 0.				
K11	PD1	ADC0_CH 1		TIM0_CC0 #3 PCNT2_S1IN #0	US1_RX #1	
L1	PB8	LFXTAL_N			US1_CS #0	

6.3 BGA112 Package Marking

In the illustration below package fields and position are shown.

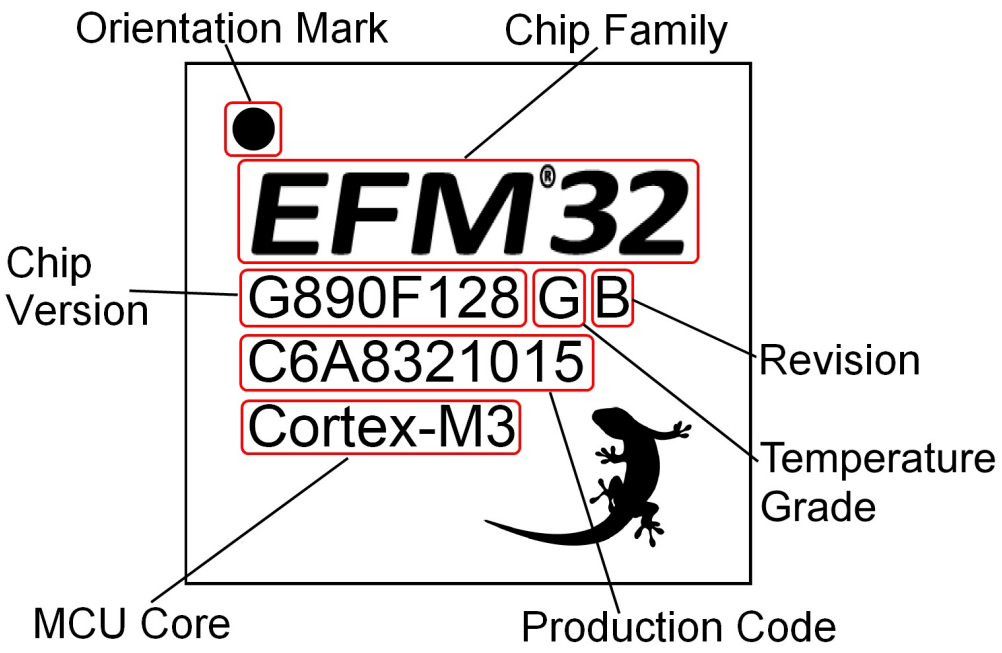

Figure 6.5. Example Chip Marking (Top View)

13.11 Revision 1.20

December 17th, 2010

This revision applies the following devices:

- EFM32G200
- EFM32G210
- EFM32G230
- EFM32G280
- EFM32G290
- EFM32G840
- EFM32G880
- EFM32G890

Increased max storage temperature.

Added data for <150°C and <70°C on Flash data retention.

Changed latch-up sensitivity test description.

Added IO leakage current.

For LQFP100 devices, updated ESD CDM value.

Added Flash current consumption.

Updated HFRCO data.

Updated LFRCO data.

Added graph for ADC Absolute Offset over temperature.

Added graph for ADC Temperature sensor readout.

13.12 Revision 1.11

November 17th, 2010

This revision applies the following devices:

- EFM32G200
- EFM32G210
- EFM32G230
- EFM32G280
- EFM32G290
- EFM32G840
- EFM32G880
- EFM32G890

Corrected maximum DAC clock speed for continuous mode.

Added DAC sample-hold mode voltage drift rate.

Added pulse widths detected by the HFXO glitch detector.

Added power sequencing information to Power Management section.